AIROC™ CYW55513/2/1 Wi-Fi & Bluetooth® combo



Low-power, 1 x 1, 2.4/5/6 GHz, IEEE 802.11ax, 20 MHz, Wi-Fi 6/6E, Bluetooth® 5.4

Infineon delivers market-proven AIROC™ Wi-Fi and Bluetooth® system on chip combos with robust, reliable, and secure wireless connectivity. Infineon is an industry leader in Wi-Fi for the IoT with over 1 billion wireless devices in the field, over the last 20 years, making AIROC™ the most deployed wireless IP in the industry.

The AIROC™ CYW55513/2/1 are a family of low-power, single-chip devices that support 1x1 single-stream, tri-band (CYW55513), dual-band (CYW55512) and single-band (CYW55511), Wi-Fi 6/6E, IEEE 802.11ax-compliant Wi-Fi MAC/baseband/radio, and Bluetooth®/Bluetooth® Low Energy 5.4. The device supports up to 1024 QAM MCS11 in 20 MHz channels delivering PHY rates up to 143 Mbps. CYW55513/2/1 provide best-in-class range/coverage by delivering up to 24 dBm of transmit power, and sensitivity down to -101.5 dBm, while supporting Wi-Fi 6/6E range improving features such as HR ER-PPDU, longer guard intervals, long OFDM symbol, and dual-carrier modulation (DCM), with Infineon range improvements for legacy rate devices. SDIO and gSPI interfaces available for interfacing to an array of A-Class (Linux/Android) andM-Class (RTOS) host processors.

CYW55513/2/1 include a Bluetooth® 5.4-compliant subsystem, with a 192 MHz Arm® Cortex®- CM33 processor, supporting Bluetooth® classic (BDR, EDR for A2DP/HFP) and Bluetooth® Low Energy audio (LC3 codec), running in hosted/controller or embedded mode where it can offload the host processor.

Additionally, the devices support Bluetooth® LE 2 Mbps, Bluetooth® LE1 Mbps, Low-Energy long-range (LR), and periodic advertising extensions. The devices integrate three power amplifiers delivering +4/+13/+19 dBm offering best-efficiency for each power level. The long range performance is delivered with industry leading -111.5 dBm LE long range (125 kbps S = 8) sensitivity, paired with the high-power integrated PA, deliver best-in-class LE long-range performance. The UART, SDIO shared with Wi-Fi, TDM/ I^2 S, PDM, and analog microphone, plus additional GPIOs are available.

The reliable, high-performance AIROC™ CYW55513/2/1 Wi-Fi and Bluetooth® 5.4 combos deliver powerful Wi-Fi capabilities that go beyond the Wi-Fi 6/6E standard for congested networks in IoT, smart home, and wearable applications and get you to market faster by speeding up the development time through a broad array of module vendors. For more information go to: CYW55513, CYW55512, CYW55511





Key features

Wi-Fi/WLAN features

- Leading transmit power: +24 dBm
- Best in class sensitivity: -101.5 dBm
- Wi-Fi 6/6E: range improving features:
 HE ER-PPDU, long guard Intervals, long OFDM symbol, DCM
- Wi-Fi 6E greenfield spectrum for lower latency and improved range
- Leading transmit power: +24 dBm
- 11ax target wake time (TWT)
- WPA2/WPA3 Personal/Enterprise
- Supports internal or external LNA/PA and antenna diversity

Bluetooth® features

- Bluetooth® 5.4 (Classic + LE)
- Embedded or hosted AIROC™ Stack
- Embedded LE isochronous channel w/LC3 CODEC for Bluetooth® LE audio
- LE 2M, LE 1M, LE LR, ADV extensions
- Three output power paths optimized for best efficiency: +4/ +13/ +19 dBm
- Support shared or dedicated antenna for optimized coexistence with Wi-Fi, 802.15.4/Thread, LTE

Interfaces

- WLAN: SDIO 3.0, shared SDIO, and GSPI
- Bluetooth®: HSUART, and shared SDIO
- Audio: 2x TDM (I2S/PCM), DMI

Coexistence

 Advanced coexistence 2-wire BTSIG WCI-2 (LTE) and 3-wire (ZigBee)

Package

- WLBGA

Key benefits

- Best range Wi-Fi 6/6E
- Power efficient Wi-Fi /Bluetooth®
- Bluetooth® 5.4/LE audio









PRODUCT BRIEF

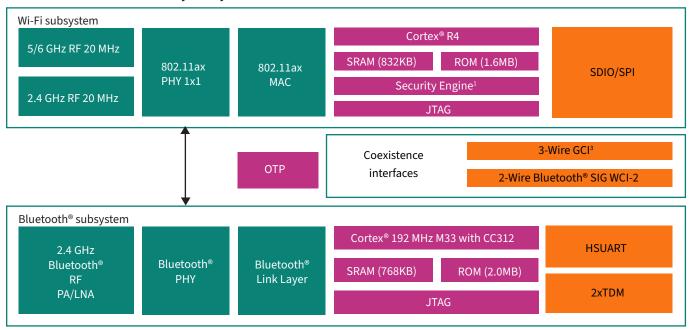
Key applications

Smart home/IoT	Smart home, IP cameras, door locks, appliances, printers, speakers, gaming, cameras	
Wearables	Smart watches, fitness bands	
Industrial/Medical Conference systems, automated meter readers, payment systems		

Infineon and module partner product summary

Product	Description	Operating temp	Package/dimensions
CYW55513IUBGT	1×1 802.11ax 2.4/5/6 GHz 20 MHz and Bluetooth® 5.4 combo	-40°C to 85°C	WLBGA
CYW55512IUBGT	1×1 802.11ax 2.4/5 GHz 20 MHz and Bluetooth® 5.4 combo	-40°C to 85°C	WLBGA
CYW55511IUBGT	1×1 802.11ax 2.4 GHz 20 MHz and Bluetooth® 5.4 combo	-40°C to 85°C	WLBGA
U-Blox MAYA-W3	U-Blox CYW55513/2/1 Modules, U.FL connectors or antennas	-40°C to 85°C	10 x 14 mm SMD
Ezurio Sona IF513	Ezurio CYW55513 Module, RF Trace or MHF4L connectors	-40°C to 85°C	12 x 16 mm M.2 1216 SMT
AW-XM606	Azurewave CYW55513 Module with RF trace	-40°C to 85°C	12x12 mm LGA
Murata 2FY	Murata CYW55513 Module	-40°C to 85°C	7.9 x 7.3 mm
WM-BAX-CYW65	USI CYW55513 SIP Module with RF trace	-40°C to 85°C	8.6x8.1 mm Molding SIP

CYW55513 wireless connectivity family



For more module options visit here.

Support in the Infineon Developer Community with online direct access to application support engineers.

Published by Infineon Technologies AG Am Campeon 1-15, 85579 Neubiberg Germany

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Public

Document number: 002-40109 REV. *A Date: 06/2024



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